

## Description

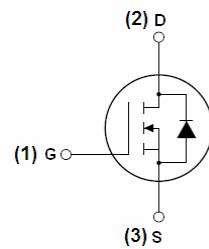
The VST08N017 uses **Super Trench** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of  $R_{DS(ON)}$  and  $Q_g$ . This device is ideal for high-frequency switching and synchronous rectification.

## General Features

- $V_{DS} = 85V, I_D = 300A$
- $R_{DS(ON)} < 2.2m\Omega @ V_{GS}=10V$
- Excellent gate charge  $\times R_{DS(on)}$  product
- Very low on-resistance  $R_{DS(on)}$
- 175 °C operating temperature
- Pb-free lead plating
- 100% UIS tested

## Application

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification



TO-247

Schematic Diagram

## Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
VST08N017-T7	VST08N017	TO-247	-	-	-

## Absolute Maximum Ratings ( $T_c=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	85	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	300	A
Drain Current-Continuous( $T_c=100^\circ C$ )	$I_D (100^\circ C)$	215	A
Pulsed Drain Current	$I_{DM}$	1200	A
Maximum Power Dissipation	$P_D$	400	W
Derating factor		2.67	W/°C
Single pulse avalanche energy <sup>(Note 5)</sup>	$E_{AS}$	2300	mJ
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 175	°C

## Thermal Characteristic

Thermal Resistance, Junction-to-Case <sup>(Note 2)</sup>	$R_{\theta JC}$	0.38	°C/W
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**Electrical Characteristics ( $T_c=25^\circ\text{C}$  unless otherwise noted)**

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=250\mu\text{A}$	85		-	V
Zero Gate Voltage Drain Current	$\text{I}_{\text{DSS}}$	$\text{V}_{\text{DS}}=85\text{V}, \text{V}_{\text{GS}}=0\text{V}$	-	-	1	$\mu\text{A}$
Gate-Body Leakage Current	$\text{I}_{\text{GSS}}$	$\text{V}_{\text{GS}}=\pm20\text{V}, \text{V}_{\text{DS}}=0\text{V}$	-	-	$\pm100$	nA
<b>On Characteristics</b> <small>(Note 3)</small>						
Gate Threshold Voltage	$\text{V}_{\text{GS(th)}}$	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_D=250\mu\text{A}$	2.5	3.5	4.5	V
Drain-Source On-State Resistance	$\text{R}_{\text{DS(ON)}}$	$\text{V}_{\text{GS}}=10\text{V}, \text{I}_D=150\text{A}$	-	1.75	2.2	$\text{m}\Omega$
Forward Transconductance	$\text{g}_{\text{FS}}$	$\text{V}_{\text{DS}}=10\text{V}, \text{I}_D=150\text{A}$	-	100	-	S
<b>Dynamic Characteristics</b> <small>(Note 4)</small>						
Input Capacitance	$\text{C}_{\text{iss}}$	$\text{V}_{\text{DS}}=40\text{V}, \text{V}_{\text{GS}}=0\text{V},$ $F=1.0\text{MHz}$	-	14500	-	PF
Output Capacitance	$\text{C}_{\text{oss}}$		-	2040	-	PF
Reverse Transfer Capacitance	$\text{C}_{\text{rss}}$		-	100	-	PF
<b>Switching Characteristics</b> <small>(Note 4)</small>						
Turn-on Delay Time	$t_{\text{d(on)}}$	$\text{V}_{\text{DD}}=40\text{V}, \text{I}_D=150\text{A}$ $\text{V}_{\text{GS}}=10\text{V}, \text{R}_G=1.6\Omega$	-	30	-	nS
Turn-on Rise Time	$t_r$		-	85	-	nS
Turn-Off Delay Time	$t_{\text{d(off)}}$		-	95	-	nS
Turn-Off Fall Time	$t_f$		-	38	-	nS
Total Gate Charge	$\text{Q}_g$	$\text{V}_{\text{DS}}=40\text{V}, \text{I}_D=150\text{A},$ $\text{V}_{\text{GS}}=10\text{V}$	-	170	-	nC
Gate-Source Charge	$\text{Q}_{\text{gs}}$		-	70	-	nC
Gate-Drain Charge	$\text{Q}_{\text{gd}}$		-	40	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage <small>(Note 3)</small>	$\text{V}_{\text{SD}}$	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_F = \text{I}_S$	-		1.2	V
Diode Forward Current <small>(Note 2)</small>	$\text{I}_S$		-	-	300	A
Reverse Recovery Time	$t_{\text{rr}}$	$T_J = 25^\circ\text{C}, \text{I}_F = \text{I}_S$ $d\text{I}/dt = 100\text{A}/\mu\text{s}$ <small>(Note 3)</small>	-	135	-	nS
Reverse Recovery Charge	$\text{Q}_{\text{rr}}$		-	380	-	nC

**Notes:**

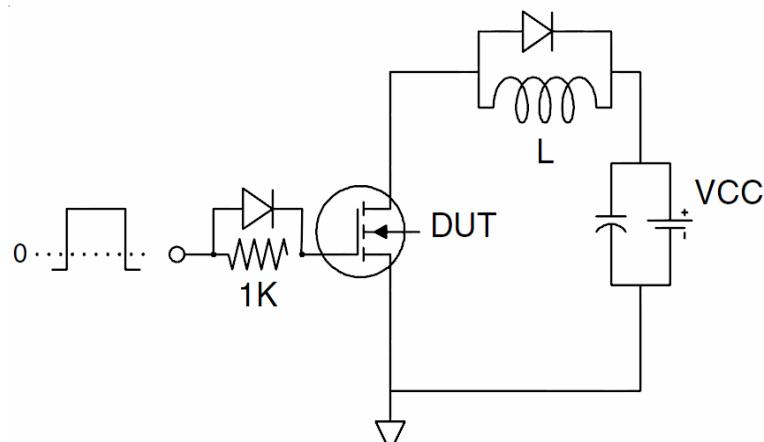
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production
5. EAS condition :  $T_J=25^\circ\text{C}, \text{V}_{\text{DD}}=42.5\text{V}, \text{V}_{\text{G}}=10\text{V}, \text{L}=0.5\text{mH}, \text{R}_g=25\Omega$

## Test Circuit

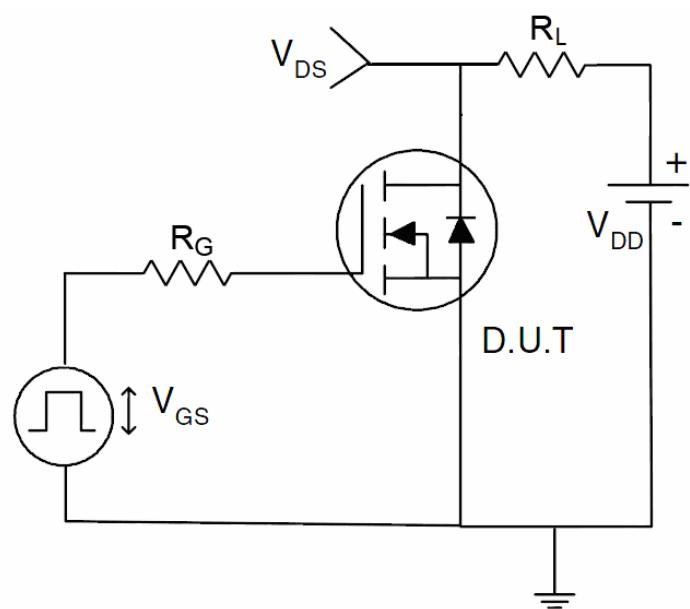
### 1) E<sub>AS</sub> test Circuit



### 2) Gate charge test Circuit



### 3) Switch Time Test Circuit



### Typical Electrical and Thermal Characteristics

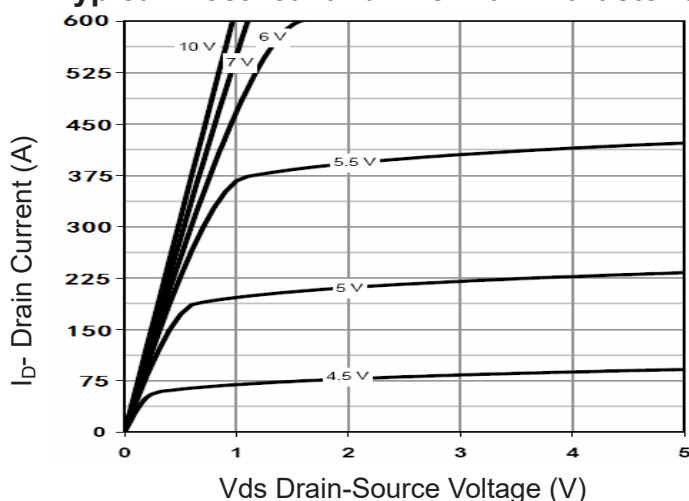


Figure 1 Output Characteristics

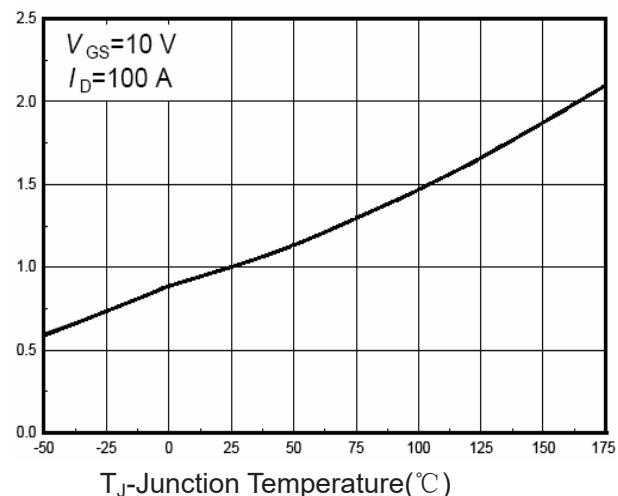


Figure 4 Rdson-JunctionTemperature

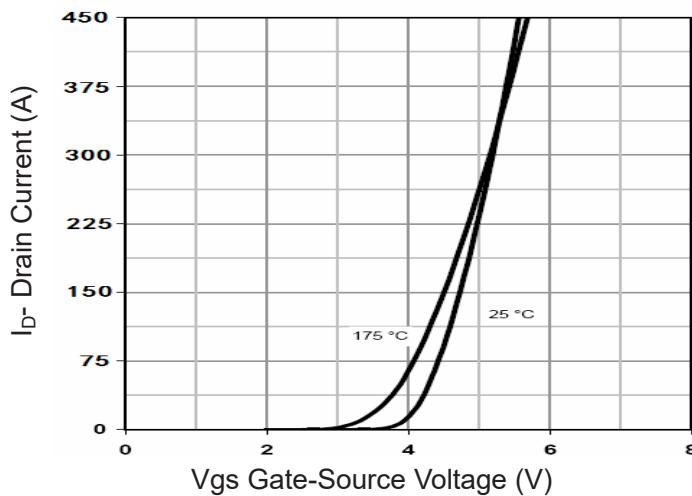


Figure 2 Transfer Characteristics

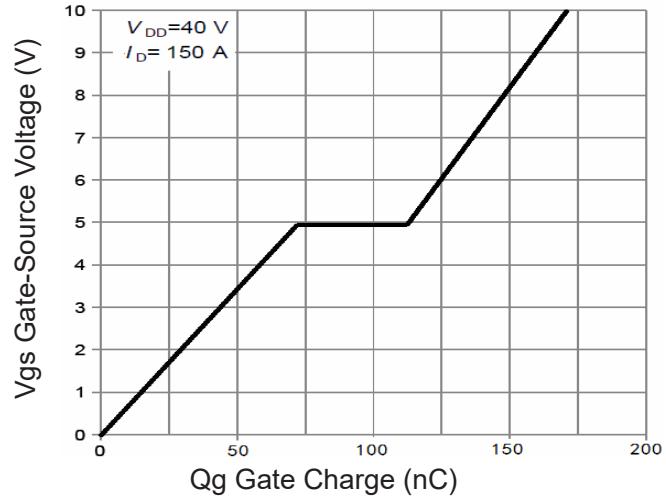


Figure 5 Gate Charge

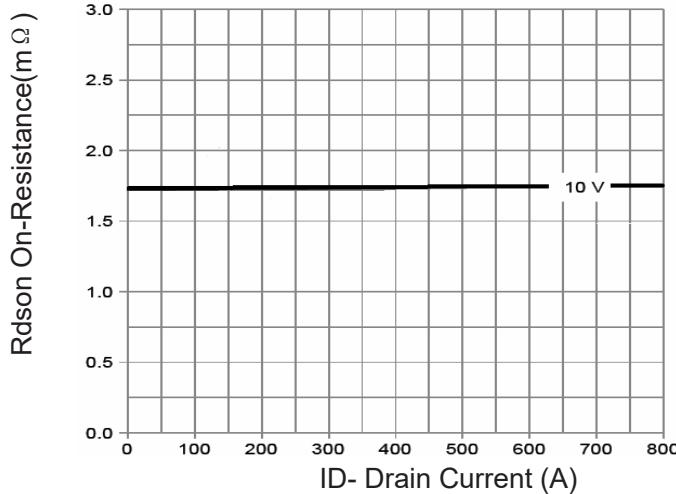


Figure 3 Rdson- Drain Current

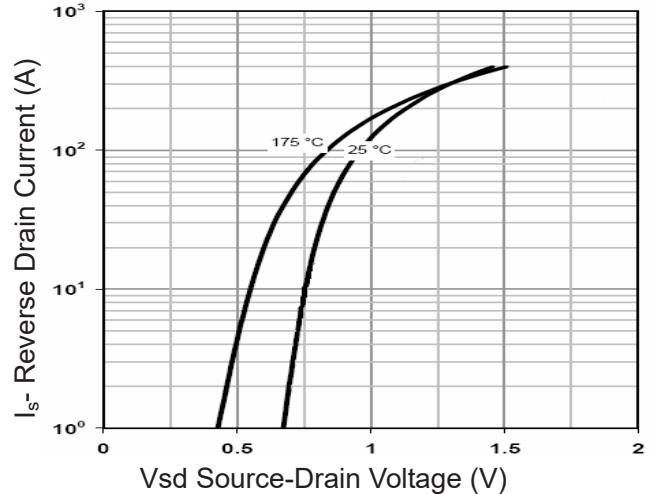
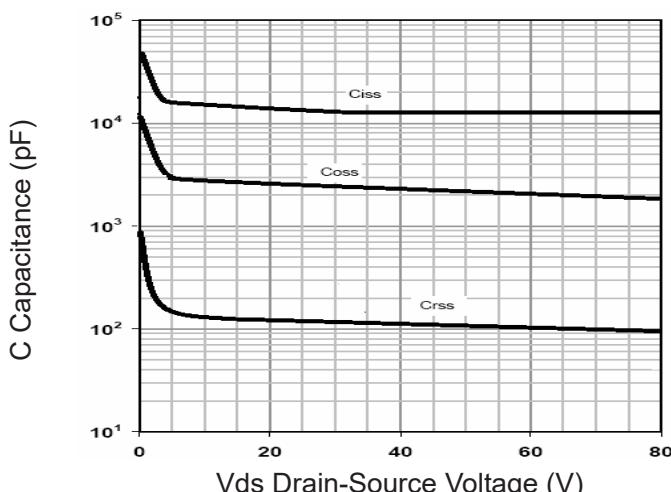
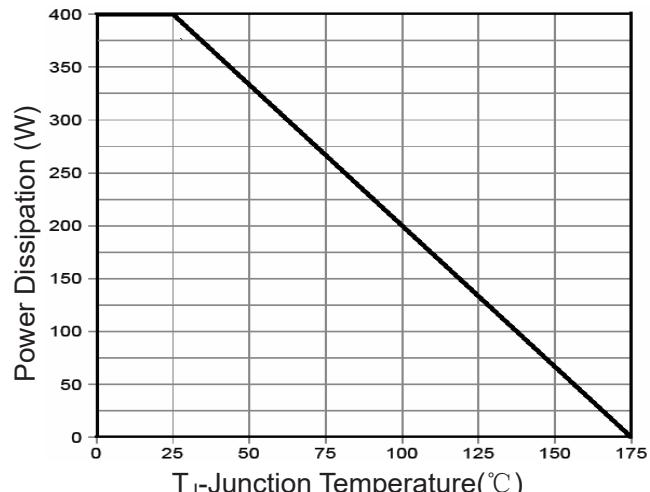
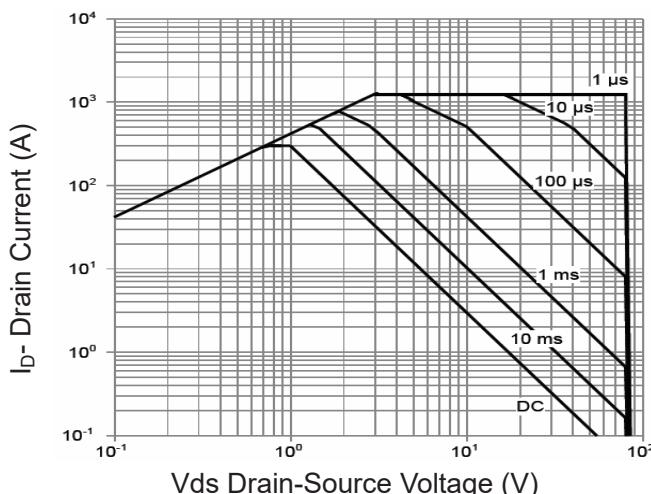
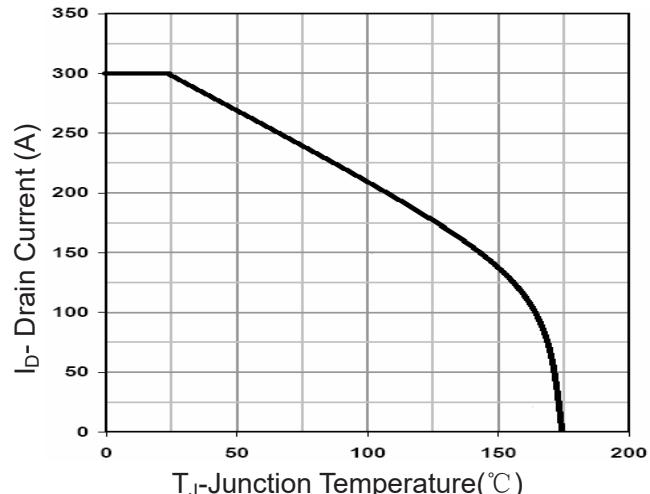
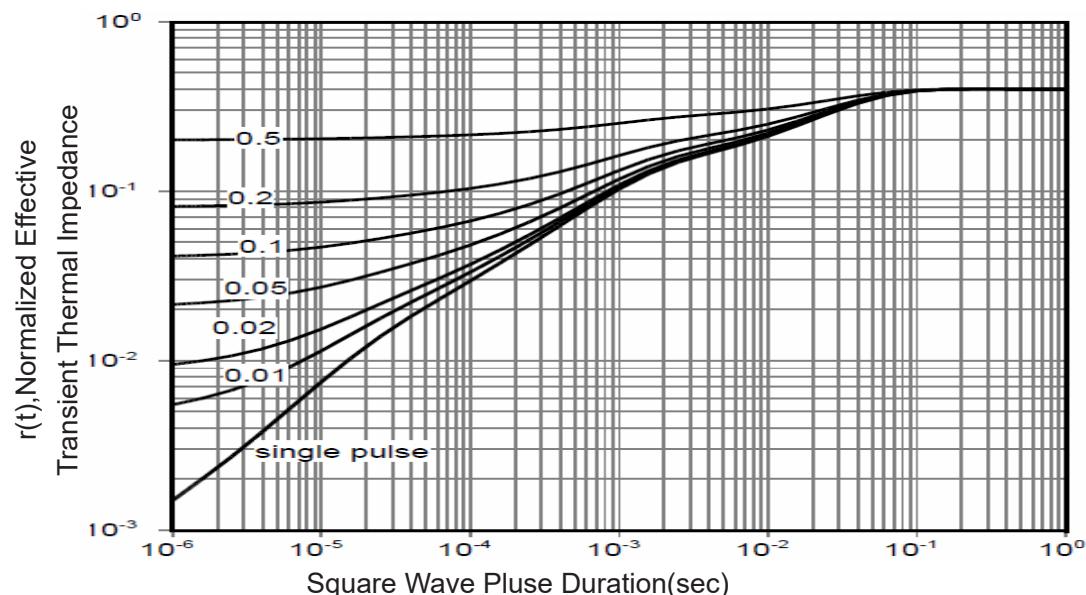


Figure 6 Source- Drain Diode Forward


**Figure 7 Capacitance vs Vds**

**Figure 9 Power De-rating**

**Figure 8 Safe Operation Area**

**Figure 10 Current De-rating**

**Figure 11 Normalized Maximum Transient Thermal Impedance**